



## Product Change Notification / ASER-13ZAYE268

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### Date:

08-Jul-2022

### Product Category:

Microprocessors

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4902 & 4902.001 Final Notice: Qualification of a new die size and mold compound for Die # 2 for selected catalog part numbers (CPN) ATSAMA5D28C-D1G-CU, ATSAMA5D27C-D1G-CU, ATSAMA5D28C-D1G-CUR, ATSAMA5D27C-D1G-CUR, ATSAMA5D27C-D5M-CU & ATSAMA5D27C-D5M-CUR available in 289L TFBGA (14x14x1.2mm) and U2 component for selected catalog part number (CPN) ATSAMA5D27-SOM1 available in 176L MODULE (40x38x6.34mm) packages.

### Affected CPNs:

[ASER-13ZAYE268\\_Affected\\_CPN\\_07082022.pdf](#)

[ASER-13ZAYE268\\_Affected\\_CPN\\_07082022.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of a new die size and mold compound for Die # 2 for selected catalog part numbers (CPN) ATSAMA5D28C-D1G-CU, ATSAMA5D27C-D1G-CU, ATSAMA5D28C-D1G-CUR, ATSAMA5D27C-D1G-CUR, ATSAMA5D27C-D5M-CU & ATSAMA5D27C-D5M-CUR available in 289L TFBGA (14x14x1.2mm) and U2 component for selected catalog part number (CPN) ATSAMA5D27-SOM1 available in 176L MODULE (40x38x6.34mm) packages.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Die Size	With change in die size. See Pre and Post Change Summary for comparison.	
Mold Compound	KE-G1250LKDS	KE-G1250NAS

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying a new die size and new mold compound.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**July 15, 2022 (date code: 2229)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2022				
Workweek	27	28	29	30	31
Qual Report Availability		x			
Final PCN Issue Date		x			
Estimated Implementation Date			x		

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**July 8, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN ASER-13ZAYE268\\_Qual Report.pdf](#)

[PCN\\_ASER-13ZAYE268\\_Pre and Post Change\\_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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ATSAMA5D27C-D5M-CU  
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